



Session Title:	[WeE2] Advanced Etching II
Session Date:	November 13 (Wed.), 2024
Session Time:	14:10-15:40
Session Room:	Room E (Sicily Room, 1F, Paradise Hotel Busan)
Session Chair:	Prof. Steve Shannon (North Carolina State Univ., USA)

[WeE2-1] [Invited] 14:10-14:40

Engineering Semiconducting and Dielectric Materials and Processes Using Integrative Methods

Peter Ventzek (Tokyo Electron America Inc., USA)

[WeE2-2] 14:40-15:00

Reactive Proton Assisted Etching for Silicon Carbide Dry Etching

Sooseong Lee ,Youngku Jin, Donghoon Kim, Jaewan Park, and MunPyo Hong (Korea Univ., Korea)

[WeE2-3] 15:00-15:20

Plasma-Enhanced Atomic Layer Etching of Tantalum Nitride with Surface Fluorination and Ar Sputtering

Hojin Kang, Sangbae Lee, Minsung Jeon, and Heeyeop Chae (Sungkyunkwan Univ., Korea)

[WeE2-4] 15:20-15:40

Optimization of BOSCH Process Using Real-Time Plasma Measurement

Chang-Min Lim, Dae Chul Jung, Junil Bae, Heejin Nam, and Chin Wook Chung (Hanyang Univ., Korea)